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<p>(21) 国際出願番号 PCT/JP00/00695</p> <p>(22) 国際出願日 2000年2月9日(09.02.00)</p> <p>(30) 優先権データ 特願平11/49450 1999年2月26日(26.02.99) JP</p> <p>(71) 出願人 (米国を除くすべての指定国について) 株式会社 日立製作所(HITACHI, LTD.)(JP/JP) 〒101-8010 東京都千代田区神田駿河台四丁目6番地 Tokyo, (JP)</p> <p>(72) 発明者 ; および</p> <p>(75) 発明者 / 出願人 (米国についてのみ) 成塚康則(NARIZUKA, Yasumori)(JP/JP) 伊藤光子(ITOU, Mitsuko)(JP/JP) 山口欣秀(YAMAGUCHI, Yoshihide)(JP/JP) 天明浩之(TENMEI, Hiroyuki)(JP/JP) 〒244-0817 神奈川県横浜市戸塚区吉田町292番地 株式会社 日立製作所 生産技術研究所内 Kanagawa, (JP)</p> <p>(74) 代理人 弁理士 作田康夫(SAKUTA, Yasuo) 〒100-8220 東京都千代田区丸の内一丁目5番1号 株式会社 日立製作所内 Tokyo, (JP)</p>		<p>(81) 指定国 CA, CN, KR, SG, US, 欧州特許 (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE)</p> <p>添付公開書類 国際調査報告書</p>
<p>(54) Title: WIRING BOARD AND ITS PRODUCTION METHOD, SEMICONDUCTOR DEVICE AND ITS PRODUCTION METHOD, AND ELECTRONIC APPARATUS</p> <p>(54) 発明の名称 配線基板およびその製造方法、半導体装置およびその製造方法並びに電子機器</p> <p>(57) Abstract A high-density wiring board having a high connection reliability and produced at low cost. The wiring board is characterized by comprising a board having an electrode and covered with an insulating layer in which a hole is made so as to expose the electrode, a wiring connected to the electrode and formed of a layer adhering to the insulating layer and made of Cr or Ti and a layer adhering to the Cr or Ti layer and made of Cu, a protective film covering the wiring and having therein a hole for soldering, and solder for external connection formed in the hole by diffusion-alloying the Cu layer and reaching the Cr or Ti layer for establishing connection.</p> <div data-bbox="860 1239 1429 1890"> <p>16...PROTECTIVE LAYER 17...SOLDER a...Sn-Ag-Cu SOLDER 17a...Sn-Cu INTERMETALLIC COMPOUND 15...STRESS RELAXATION LAYER</p> </div>		

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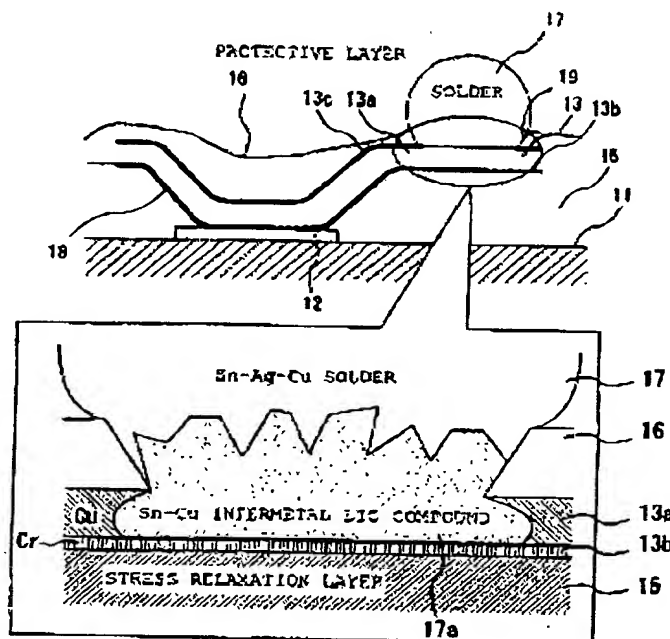
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WO0052755

WIRING BOARD AND ITS PRODUCTION METHOD, SEMICONDUCTOR DEVICE AND ITS PRODUCTION METHOD, AND ELECTRONIC APPARATUS
HITACHI, LTD.

Inventor(s): NARIZUKA, Yasumori ; ITOU, Mitsuko ; YAMAGUCHI, Yoshihide ; TENMEI, Hiroyuki
Application No. JP0000695 JP, Filed 20000209, A1 Published 20000908

Abstract: A high-density wiring board having a high connection reliability and produced at low cost. The wiring board is characterized by comprising a board having an electrode and covered with an insulating layer in which a hole is made so as to expose the electrode, a wiring connected to the electrode and formed of a layer adhering to the insulating layer and made of Cr or Ti and a layer adhering to the Cr or Ti layer and made of Cu, a protective film covering the wiring and having therein a hole for soldering, and solder for external connection formed in the hole by diffusion-alloying the Cu layer and reaching the Cr or Ti layer for establishing

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connection.

Int'l Class: H01L02312; H01L02315 H05K00334

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